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June 25, 2026

The Honorable Lisa R. Barton
Secretary to the Commission
U.S. International Trade Commission
500 E Street S.W.
Washington, D.C. 20436

Via EDIS

Re: *Certain Dynamic Random Access Memory (DRAM) Devices, Products Containing the Same, and Components Thereof (II)*, Docket No. 3915 –
Supplemental Information to Complaint

Dear Secretary Barton:

On behalf of Netlist, Inc. (“Netlist” or “Complainant”), we write to provide the following supplemental information regarding the Complaint filed on June 16, 2026, in Investigation Docket No. 337-3915. Enclosed with this letter as supplemental information are exhibits, which are listed in the table appended to this letter.

1. Certified Versions of Patent Assignment Records and Prosecution Histories.

Complainant has retrieved certified copies of the assignment records for the Asserted Patents.¹ These records are being delivered to the Commission pursuant to Commission Rule 210.12(a)(9)(ii). *See* Ex. A (assignment record for the ’537 Patent) and Ex. B (assignment record for the ’937 Patent).

2. Additional Exhibits to Accompany Infringement and Domestic Industry Charts and the Park Declaration.

The Complaint includes three Infringement charts for the Asserted Patents, *see* Ex. 9, 10, and 11, as well as three Domestic Industry charts, *see* Ex. 25, 44, and 45. The charts rely on exhibits that were mentioned in the cover letter, as well as the letter requesting confidential treatment, but were inadvertently omitted during the filing of the Complaint. These claim chart exhibits, CC-01 to CC-60, as well as CC-27C, CC-29C, CC-35C, CC-36C, and CC-37C² (confidential versions), and

¹ The Asserted Patents are U.S. Patent Nos. 12,646,537 (“the ’537 patent”) and 12,650,937 (“the ’937 patent”).

² Exhibit CC-37C was inadvertently omitted from our June 15, 2026 letter requesting confidential treatment. Because this exhibit contains information which qualifies as confidential business information under Commission Rule 201.6, we respectfully request that it also be treated as confidential.

an updated table of exhibits are being delivered to the Commission with this supplement. Additionally, Exhibit 8 submitted with the Complaint—the declaration of Devon Park—inadvertently omitted printouts of the exhibits referenced in that declaration. A complete copy of Exhibit 8, which consists of the unchanged declaration and the accompanying exhibits, is being delivered to the Commission.

3. Redacted Versions of Confidential Exhibits.

As requested, we are providing redacted versions of Confidential Exhibits 9-11, 24, and 44-45 (the infringement charts, domestic industry charts) that redact only the information qualifying as confidential business information under Commission Rule 201.6. We are also including a redacted version of Confidential Exhibit 46, the declaration supporting domestic industry, with redactions performed on a line-by-line basis.

4. Additional Evidence of Importation into the United States.

We understand that no request to supplement the Complaint regarding the importation of Samsung HBM was made and that the information provided in paragraphs 80-89 of the Complaint adequately addresses HBM importation. Should further evidence be needed, the following paragraphs provided in this letter address demonstrate that since June 2, 2026, Samsung continues to import, sell for importation, and/or sell within the United States after importation its HBM: 84.1-84.2, 85.1-85.2, 87.1, and 89.1-89.2.

Additionally, Complainant amends paragraph 77 of the Complaint as follows:

77.1. Exhibit 16.1 includes receipts for the domestic purchase of accused DDR5 RDIMMs, part number M321R4GA3EB2-CWMCJ, which occurred on June 15, 2026, after the issuance of the '937 Patent. The purchased DDR5 RDIMMs are labeled as being made by Samsung in Korea. The order and shipping paperwork indicate that the products were shipped to an address within the United States and received there on June 16, 2026, demonstrating that the Samsung Respondents import the product, sell it for importation, and/or sell it within the United States after importation. *Id.*

77.2. Exhibit 16.2 includes receipts for the domestic purchase of accused DDR5 MRDIMMs, part number M327R4GA3EB0-CLVXB, which occurred on June 19, 2026, after the issuance of the '937 Patent. The purchased DDR5 MRDIMMs are labeled as being made by Samsung in Korea. The order and shipping paperwork indicate that the products were shipped to an address within the United States and received there on June 22, 2026, demonstrating that the Samsung Respondents import the product, sell it for importation, and/or sell it within the United States after importation. *Id.*

77.3. Exhibit 16.3 includes receipts for the domestic purchase of accused DDR5 RDIMMs, part number M321R8GA0EB2-CCPWC, that are “dual-label” Samsung and Super Micro (i.e., Samsung DDR5 RDIMMs which are rebranded and resold by Super Micro with both companies listed on the product label). The purchase occurred on June 22, 2026, after the issuance of the '937 Patent. The purchased dual-label DDR5 RDIMMs are labeled as being made by Samsung in Vietnam and bear Super Micro’s name on them as well. The order and shipping

paperwork indicate that the products were shipped to an address within the United States and received there on June 23, 2026, demonstrating that *both* Samsung Respondents and Super Micro import the product, sell it for importation, and/or sell it within the United States after importation. *Id.*

a. Google Imports the Accused Products into the United States.

i. Importation of Products that Infringe the '537 Patent.

Complainant amends paragraph 84 of the Complaint as follows:

84.1. The following evidence shows that Google has continued importing its Tensor Processing Units (TPUs), which include Samsung HBM, since June 2, 2026 (the date that the '537 Patent issued). A June 14, 2026 report observed that Samsung already supplies the HBM used in Google's existing TPUs. Ex. S-1. Earlier this year, Samsung agreed to supply its HBM4 memory to Google and Broadcom through 2026, as well as "suppl[ying] more fifth-generation HBM (HBM3E) chips for Google's current TPU (sixth-generation)." Ex. S-2. And Google has started selling and leasing its servers with TPUs to Anthropic; the vast majority of this TPU capacity "will be sited in the United States." Ex S-3 (Anthropic expands partnership with Google and Broadcom). For example, a June 19, 2026, report explained how Google has an agreement with Anthropic, by which Google leases Broadcom-designed TPUs to Anthropic in various U.S. data centers. Ex. S-4 (identifying data centers in Louisiana, Texas, and western New York that "rent computing power from thousands of Google's tensor processing units, or TPUs, to Anthropic").

84.2. Additionally, as reflected in the public interest statement of Google, filed in the ITC Investigation No. 337-TA-1472, the importation of infringing Samsung HBM by Google into the United States is ongoing, including after the issuance of the '537 Patent on June 2, 2026. *See* EDIS Doc. ID 864975 p. 2 (acknowledging that Google servers and storage systems contain Samsung HBM). Google stated in its public interest submission in the -1472 Investigation that it is "unmatched in its supply of critical TPUs and GCPs" and that "Google's ability to supply these products [domestically] requires a sufficient supply of HBM" which incorporates memory from Samsung among other suppliers. *See id.* at 4. Google does not contest anywhere in this submission that it continues to receive, incorporate, and rely on the accused Samsung HBM packages in the United States and in fact confirms that its products are "downstream accused Google products." *Id.* at 2. Further, even if servers with Google TPUs could be purchased, they typically cost hundreds of thousands of dollars making their acquisition for this Investigation not practical.

ii. Importation of Products that Infringe the '937 Patent.

Complainant next amends paragraph 84 of the Complaint as follows:

84.3. The following evidence shows that Google imports Samsung DIMMs and products that contain Samsung DIMMs, into the United States since June 9, 2026 (the date that the '937 Patent issued). By way of example, the Google Cloud Platform (GCP) virtual machine services utilize Intel Xeon 6 processors and DDR5 memory, which, on information and belief, includes Samsung's accused RDIMMs and MRDIMMs. *See* Ex. S-17, p. 1 (showing that C4 systems have up to 2.2TB of DDR5 memory); *see also* Ex. S-28 pp. 13-15 (showing physical locations of C4

machines in Iowa and Virginia (last visited June 23, 2026)). On information and belief, Google purchases these Accused Products from Samsung, imports them, and uses them in these Google products and services, domestically in such states as Oregon, California, Utah, Nevada, and Virginia. *See* Ex. S-18 p. 2 (identifying specific regional domains where Google Cloud products are located in the United States (last visited June 23, 2026)); Ex. S-19, pp. 3-4 (showing nine regions in the United States where Google Cloud data centers operate (last visited June 23, 2026)).

84.4. Additionally, as reflected in the public interest statement of Google, filed in the -1472 Investigation, the importation of infringing Samsung RDIMMs and MRDIMMs by Google into the United States is ongoing, including after the issuance of the '937 Patent on June 9, 2026. *See* EDIS Doc. ID 864975 p. 4 (acknowledging that Google servers and storage systems contain Samsung DIMMs). Google does not contest anywhere in this submission that it continues to receive, incorporate, and rely on the accused Samsung RDIMMs in the United States and in fact confirms that its products are “downstream accused Google products.” *See id.* at 2. Further, even if servers with Google servers with Samsung RDIMMs could be purchased, they typically cost hundreds of thousands of dollars making their acquisition for this Investigation not practical.

b. Super Micro Imports the Accused Products into the United States.

i. Importation of Products that Infringe the '537 Patent.

Complainant next amends paragraph 85 of the Complaint as follows:

85.1. Since June 2, 2026 (the date that the '537 Patent issued), Super Micro has continued to import infringing Samsung HBM into the United States. As indicated in paragraph 85 of the Complaint, the H13 and H14 Super Micro servers include and use AMD's Instinct accelerators (MI300X/MI325X/MI350X) as evidenced by the Super Micro datasheets. For example, Super Micro offers for sale its H13 system, model No. AS -8125GS-TNMR2, with the AMD Instinct MI300X Accelerator and this system includes “[i]ndustry-leading 1.5TB HBM3 GPU memory.” Ex. S-20 (H13 datasheet). The MI300X accelerator uses Samsung HBM3. Ex. S-24 (noting “the first commercial instance of Samsung’s HBM3 memory, integrated into AMD’s MI300X AI accelerator”). That very system, model No. AS -8125GS-TNMR2, is listed as being available for purchase on Super Micro’s eStore website, with shipping “within 3-5 business days.” Ex. S-22 p. 4 (printout of https://store.supermicro.com/us_en/systems/gpu.html (last visited June 23, 2026)). Similarly, Super Micro’s H14 system design with AMD Instinct MI350X accelerators includes “[i]ndustry-leading 2.3 TB of HBM3E GPU memory in a single server node.” Ex. S-21 (H14 datasheet)). Samsung “has confirmed that its HBM3E memory is used in the new Instinct MI350X and MI355X AI accelerators.” Ex. S-25. One of Super Micro’s H14 systems with Samsung HBM3E, model No. AS -8126GS-TNMR, is currently listed as “in stock” on the Super Micro eStore, with a shipping time of 3-5 business days. Ex. S-23 p. 1 (printout of https://store.supermicro.com/us_en/8u-gpu-superserver-as-8126gs-tnmr.html (last visited June 23, 2026)).

85.2. Additionally, as reflected in its public interest statement, filed in the -1472 Investigation, Super Micro’s importation of Samsung HBM is ongoing, including after the issuance of U.S. Patent No. 12,646,537, on June 2, 2026. *See* EDIS Doc. ID 864946 p. 3 (Super Micro) (acknowledging that Super Micro servers and storage systems contain Samsung HBM). Further,

even if such servers from Super Micro could be purchased, they typically cost hundreds of thousands of dollars making their acquisition for this Investigation not practical.

ii. Importation of Products that Infringe the '937 Patent.

Complainant next amends paragraph 85 of the Complaint as follows:

85.3. Since June 9, 2026 (the date that the '937 Patent issued), Super Micro has continued to import infringing Samsung RDIMMs and MRDIMMs into the United States. As seen in Exhibit 16.3, Super Micro resells a dual-label Samsung / Super Micro DDR5 RDIMM that is originally manufactured by Samsung in Korea.

85.4. Additionally, as indicated in paragraph 85 of the Complaint, the H13 and H14 Super Micro servers include and use AMD's Instinct accelerators (MI300X/MI325X/MI350X)—as evidenced by the Super Micro datasheets. For example, Super Micro offers for sale its H13 system, model No. AS -8125GS-TNMR2, with "24 DIMM slots for up to 1 TB ECC DDR5-4800 RDIMM." Ex. S-20 p. 2 (H13 datasheet). That very system, model No. AS -8125GS-TNMR2, is listed as being available for purchase on Super Micro's eStore website, with shipping "within 3-5 business days." Ex. S-22, p. 4 (printout of https://store.supermicro.com/us_en/systems/gpu.html (last visited June 23, 2026)). Similarly, Super Micro's H14 systems have memory capacity that supports up to "24 DIMM slots [of] ECC DDR5-6000 RDIMM." Ex. S-21 (H14 datasheet). One of those H14 systems, model No. AS -8126GS-TNMR, is listed as "in stock" on the Super Micro eStore, also with a shipping time of 3-5 business days. Ex. S-23 p. 1 (printout of https://store.supermicro.com/us_en/8u-gpu-superserver-as-8126gs-tnmr.html (last visited June 23, 2026)).

c. NVIDIA Imports the Accused Products into the United States.

i. Importation of Products that Infringe the '537 Patent.

Complainant next amends paragraph 87 of the Complaint as follows:

87.1. Since June 2, 2026 (the date that the '537 Patent issued), NVIDIA is continuing to import, sell for import, or sell after importation products containing Samsung HBM. Specifically, on June 5, 2026, NVIDIA CEO Jensen Huang confirmed that Samsung Electronics passed certification to supply HBM4 high-bandwidth memory for the company's next-generation Vera Rubin AI accelerator platform, marking the first public acknowledgment of approvals for Samsung. Ex. S-11. NVIDIA held its Global Technology Conference in Taipei on June 1-4, 2026. During the keynote, Mr. Huang confirmed that Samsung Electronics supplies "sixth-generation HBM4 memory for [NVIDIA's] Vera Rubin" chips, providing "approximately 25 to 30 percent" of the HBM. Ex. S-12; Ex. S-13 (June 4, 2026, report observing that "Samsung Electronics passed Nvidia's HBM4 quality certification first in the industry and has begun mass production and supply," with NVIDIA's Vera Rubin systems slated to "begin shipping to [Amazon], Google Cloud, Microsoft Azure and Oracle in the summer of 2026"); Ex. S-14 (Tech Times June 9, 2026 article reporting that "[i]ndustry analysts estimate Samsung holds approximately 25 to 30 percent of the HBM4 volume allocated for Vera Rubin" and that NVIDIA CEO "Huang arrived in Seoul on June 5 and confirmed at the airport that [Samsung] had passed qualification and [was] in active

production for Vera Rubin, with the first customer shipments scheduled for Q3 2026”). In fact, a June 16, 2026, Startup Fortune article explained that Samsung has “pushed hard into HBM4, with reports from TechRadar and other industry outlets saying its 11.7Gbps modules have been lined up for Nvidia’s Vera Rubin platform.” Ex. S-15. Moreover, NVIDIA is unable to produce its more advanced chips in the United States—in addition to Korean-made HBM, the manufacturing process for Blackwell and Vera Rubin chips necessarily requires the importation of the products. Ex. S-16 (NVIDIA chip wafers are “shipped back to TSMC’s facilities in Taiwan” for completion of certain critical final steps). And “Bloomberg data showing Asian suppliers now account for roughly 90% of Nvidia’s production costs [which] includes TSMC fabrication, . . . Samsung memory, and server assembly from companies such as Foxconn and Quanta.” Ex. S-15 (Startup Fortune).

ii. Importation of Products that Infringe the ’937 Patent.

Complainant next amends paragraph 87 of the Complaint as follows:

87.2. On information and belief, since June 9, 2026 (the date that the ’937 Patent issued), NVIDIA is continuing to import, sell for import, or sell after importation into the United States, Samsung RDIMMs. NVIDIA’s DGX B300 service manual, dated as recently as April 30, 2026, includes a chapter on DIMM upgrade and replacement. Ex. S-26 pp. 35-38 (Chapter 7). The manual states that NVIDIA Enterprise Support will provide “replacement DIMM[s]” and that the user can “[d]etermine the DIMM manufacturer” by running certain commands. *Id.* p. 36 (instructing the user to “[r]equest a replacement DIMM from NVIDIA Enterprise Support, specifying the manufacturer”); *see Certain Photovoltaic Trunk Bus Cable Assemblies & Components Thereof*, USITC Inv. No. 337-TA-1438, Final Initial Determination, 2026 WL 575455, at *35 (Feb. 6, 2026) (permitting reliance on technical documents if customary to do so in the industry, absent evidence of superseding correction or revocation); *see also Bissell, Inc. v. Int’l Trade Comm’n*, 175 F.4th 1327, 1335 (Fed. Cir. 2026) (similar); *Golden Blount, Inc. v. Robert H. Peterson Co.*, 438 F.3d 1354, 1364 (Fed. Cir. 2006) (similar).

d. Broadcom Imports the Accused Products into the United States.

i. Importation of Products that Infringe the ’537 Patent.

Complainant next amends paragraph 89 of the Complaint as follows:

89.1. Since June 2, 2026 (the date that the ’537 Patent issued), Broadcom is continuing to import, sell for import, or sell after importation into the United States, products containing Samsung HBM, specifically Google’s TPU processors. On its June 3, 2026, earnings call, the CEO of Broadcom discussed supplying Google with TPU processors that use HBM. Ex. S-5 (June 12, 2026 article noting that Broadcom may be unable “to meet all of Google’s demand”); Ex S-6 (stating that Broadcom has “been able to secure supply of [HBM] for our needs 2026, 2027”). Earlier this year, Samsung agreed to supply its HBM4 memory to Google and Broadcom through 2026, as well as “suppl[ing] more fifth-generation HBM (HBM3E) chips for Google’s current TPU (sixth-generation).” Ex. S-2. “Half of Samsung’s HBM4 chips will be supplied to Broadcom, while the rest will be supplied to Nvidia for its Rubin GPU.” *Id.* “Broadcom, serving as the design and production hub for Google’s TPU, plays a critical gatekeeping role in *procuring*, integrating, and certifying core components like HBM.” Ex. S-7 (The CHOSUN daily) (emphasis added). And

Broadcom has a “compute agreement” with Google, in which Google leases Broadcom-designed TPUs to Anthropic in various U.S. data centers. Ex. S-4 (identifying data centers in Louisiana, Texas, and western New York that will “rent computing power from thousands of Google’s tensor processing units, or TPUs, to Anthropic”).

89.2. Additionally, since June 2, 2026, Broadcom is helping OpenAI develop a new custom AI chip—called Titan—which will be manufactured by TSMC and use Samsung HBM. Ex. S-8 (June 15, 2026 article describing Broadcom’s role in co-designing custom AI accelerators that use Samsung HBM). And a second generation of Titan will have “a dedicated HBM4 memory supply chain secured through Samsung, . . . targeting mass production in the second half of 2026.” Ex. S-9 (OpenAI’s Titan Chip and Samsung HBM4 Deal). OpenAI is planning to deploy its AI chip in its Stargate data centers located within the United States. *E.g.*, Ex. S-10 (OpenAI in talks to lease 10GW data center from SB Energy in Ohio).

ii. **Importation of Products that Infringe the ’937 Patent.**

Complainant next amends paragraph 89 of the Complaint as follows:

89.3. On information and belief, since June 9, 2026 (the date that the ’937 Patent issued), Broadcom is continuing to import, sell for import, or sell after importation into the United States, Samsung RDIMMs. Broadcom offers cloud computing services through VMware by Broadcom and, as part of those services, it maintains a “Broadcom compatibility guide,” which “provides comprehensive partner product compatibility lists for VMware infrastructure.” Ex. S-27 (Broadcom Compatibility Guide). The guide includes “detailed lists [which] show actual vendor devices that are either physically tested or are similar to the devices tested by VMware or VMware partners.” *Id.* Those lists include Super Micro servers, such as the H14 systems—referenced in ¶ 85.4, above—that have memory capacity that supports up to “24 DIMM slots [of] ECC DDR5-6000 RDIMM.” Ex. S-21 (H14 datasheet). On information and belief, in order to assure compatibility, Broadcom imports servers and systems containing Samsung RDIMMs for internal testing. Ex. S-27 (Broadcom Compatibility Guide).

Thank you for your consideration and attention to this matter. Please contact me if you have any questions.

Respectfully submitted,

STERNE, KESSLER, GOLDSTEIN & FOX P.L.L.C.



Daniel E. Yonan
Director

Counsel for Complainant Netlist, Inc.

Enclosures

Exhibit No.	Description
8 (Part 1)	Devon Park Declaration with Exhibits
8 (Part 2)	Devon Park Declaration with Exhibits
9	Claim Chart 001 – ‘537 Infringement Contentions HBM (public version)
10	Claim Chart 002 – ‘937 Infringement Contentions RDIMM (public version)
11	Claim Chart 003 – ‘937 Infringement Contentions MRDIMM (public version)
16.1	RDIMM Importation Evidence
16.2	MRDIMM Importation Evidence
16.3	Dual Label RDIMM Importation Evidence
24	DI Chart 003 – 12,650,937 MDRIMM (public version)
44	DI Chart 001 – 12,646,537 HBM (public version)
45	DI Chart 002 – 12,650,937 RDIMM (public version)
46	Sasaki Declaration (public version)
A	US Patent No. 12,646,537 Assignment
B	US Patent No. 12,650,937 Assignment
S-1	Google is in talks with Samsung to build next-gen ‘Icefish’ TPU on 1.4nm and 2nm process split
S-2	Samsung could earn billions by supplying HBM4 chips for Google’s TPU
S-3	Anthropic expands partnership with Google and Broadcom
S-4	Google is using Nvidia’s playbook to break its AI-chip grip
S-5	Google TPU orders shift as MediaTek Marvell and Broadcom split market
S-6	Earnings call transcript Broadcom Q2 2026
S-7	Samsung Secures HBM4 Supply Contract for Google TPU
S-8	What Does Broadcom Do
S-9	OpenAI Titan Custom AI Chip Samsung HBM4
S-10	OpenAI in talks to lease 10GW data center from SB Energy
S-11	Nvidia certifies Samsung, SK Hynix and Micron for Vera Rubin
S-12	Nvidia Vera Rubin Hits Full Production With Samsung, SK Hynix, Micron named HBM4 Suppliers
S-13	Nvidia Rubin Hits Full Production With Samsung... AI in Asia
S-14	Samsung Pursues Nvidia HBM4E Supply and LP40 Foundry Work After Seoul Bilateral
S-15	Asia’s chip stocks are beating Nvidia because the real AI bottleneck was never the GPU
S-16	TSMC produces the first Nvidia Blackwell GPU in the US
S-17	General-purpose machine family for Compute Engine
S-18	Locations of Google Data Centers
S-19	Google Data Centers
S-20	Super Micro H13 Datasheet
S-21	Super Micro H14 Datasheet
S-22	Super Micro GPU Systems (AS -8125GS-TNMR2) – Super Micro eStore
S-23	GPU AS -8126GS-TNMR_Rackmount Server – Super Micro eStore

S-24	TechInsights' Analysis of AMD's MI300X Reveals Samsung HBM3
S-25	AMD Uses Samsung's HBM3E in Instinct MI350x
S-26	NVIDIA Dgxb300-service-manual
S-27	Broadcom - VMware Hardware Compatability Guide
S-28	Bare metal instances _ Compute Engine
CC-1	Semiconductors DRAM HBMs
CC-2	Samsung HBM4
CC-3	Samsung HBM3E
CC-4	Leading Innovation HBM3E
CC-5	HBM3 Icebolt
CC-6	Perfect Harmony
CC-7	HBM3
CC-8	HBM2 Aquabolt
CC-9	Samsung HBM2E Flashbolt
CC-10	TPU Architecture
CC-11	IPR2022-1427 EX2030
CC-12	IPR2022-1427 EX2029
CC-13	Design Paper
CC-14	Sohn 2016
CC-15	JESD238A
CC-16	JESD270-4
CC-17	JESD235D
CC-18	Ryu 2023
CC-19	Asifuzzaman 2021
CC-20	Samsung completes 16-stack HBM sample
CC-21	High Bandwidth Memory for Data-intensive Computing _ Samsung Semiconductor Glob
CC-22	Samsung Starts Producing 8-Gigabyte High Bandwidth Memory-2
CC-23	Oh 2020
CC-24	JESD305A
CC-25	Samsung 64GB DDR5
CC-26	Samsung High Bandwidth Memory Illustration
CC-27	JESD82-552 (Redacted in its Entirety)
CC-27C	JESD82-552
CC-28	JESD82-514.01
CC-29	JESD82-512 (Redacted in its Entirety)
CC-29C	JESD82-512
CC-30	Samsung MCRDIMM
CC-31	SK hynix Module
CC-32	SK hynix MRDIMM
CC-33	DDR5 DIMMs Netlist
CC-34	Lightning DDR5 DIMM Netlist
CC-35	Netlist DDR5 VLP RDIMM Datasheet 1.1 (Redacted in its Entirety)
CC-35C	Netlist DDR5 VLP RDIMM Datasheet 1.1

CC-36	Netlist DDR5 Overclock RDIMM Datasheet 1.0 (Redacted in its Entirety)
CC-36C	Netlist DDR5 Overclock RDIMM Datasheet 1.0
CC-37	JESD82-542 (Redacted in its Entirety)
CC-37C	JESD82-542
CC-38	SK hynix Develops Industry's First 12-Layer HBM3
CC-39	SK hynix Develops World's Best Performing HBM3E
CC-40	SK hynix HBM Products
CC-41	SK hynix Begins Volume Production of 12-Layer HBM3E
CC-42	DCD SK hynix Article
CC-43	IEEE Paper1
CC-44	IEEE Paper2
CC-45	IEEE Paper3
CC-46	IEEE Paper4
CC-47	IEEE Paper5
CC-48	IEEE Paper6
CC-49	SK hynix The Era of High Bandwidth Memory
CC-50	SK hynix 2018 HBM Presentation
CC-51	SK hynix 2025 HBM Presentation
CC-52	Semiconductor Back-end Process 4 Packages, Part 2
CC-53	Rulebreakers' Revolutions Design Scheme Elevates HBM3E
CC-54	SK hynix Develops World's Best Performing HBM3E
CC-55	SK hynix Completes World-First HBM4 Development
CC-56	Become a Semiconductor Expert with SK hynix – HBM
CC-57	SK hynix Presents AI Memory, HBM4 at Supercomputing 2025
CC-58	Continuing to Make HBM History
CC-59	SK hynix 2014 HBM Presentation
CC-60	SK hynix HBM3 Products